

REMARKS

Claims 9, 14, 15 and 22 are pending in this application.

By this Amendment, claim 21 is canceled. Claim 9 is amended to incorporate the subject matter recited in canceled claim 21, and for better clarity. Claim 22 is amended to depend from claim 9.

Reconsideration of the application is respectfully requested.

Entry of the amendments is proper under 37 CFR §1.116 since the amendments: (a) place the application in condition for allowance (for the reasons discussed herein); (b) do not raise any new issue requiring further search and/or consideration (as the amendments amplify issues previously discussed throughout prosecution); and (c) place the application in better form for appeal, should an appeal be necessary. Entry of the amendments is thus respectfully requested.

The Office Action rejects claims 9, 14, 15, 21 and 22 under 35 U.S.C. §103(a) over U.S. Patent Publication 2002/0151161 to Furusawa in view of U.S. Patent 5,666,270 to Matsuda et al. This rejection is respectfully traversed.

Claim 9 is amended to incorporate the subject matter recited in claim 21, as outlined above. Furusawa and Matsuda, either individually or in combination, do not disclose or suggest the subject matter recited in claim 21, currently recited in claim 9.

The Office Action, when rejecting claim 21, asserts that Furusawa discloses in Fig. 4 discharging droplets on an insulating layer. However, Furusawa only discloses discharging fine particle dispersion solution 14 in Fig. 4. The fine particle dispersion solution 14 is not resin.

On the other hand, the "droplets" recited in claim 21 are droplets that includes "a precursor of UV-hardening resin," as defined in claim 9. Furusawa's fine particle dispersion

solution is not resin, as discussed above. Therefore, Furusawa does not disclose or suggest the subject matter recited in claims 9 and 21.

Matsuda discloses UV-hardening silicone resin layer 60 at the portions corresponding to the position of electrode pad 32. See Fig. 7b and col. 5, lines 21-26. However, the silicone resin layer 60 resides on the electrode pad 32, which is not an insulating layer. Matsuda discloses in Fig. 4 a bump sandwiched between semiconductor layer 31 and conductive layer 36. See col. 3, lines 44-53. However, there is a metallic layer 34 between the bump 35 and the semiconductor element 31. Thus, the bump 35 is not sandwiched between an insulating layer and a conductive layer.

For at least the above reasons, Furusawa and Matsuda, either individually or in combination, do not disclose or suggest discharging droplet on an insulating layer, much less discharging the droplets directly on the insulating layer without a conductor between the droplets and the insulating layer, as recited in claim 9. Therefore, Furusawa and Matsuda, either individually or in combination, do not disclose or suggest the subject matter recited in claim 9, and claims 14, 15 and 22 depending therefrom. Accordingly, withdrawal of the rejection of claims 9, 14, 15 and 22 under 35 U.S.C. §103(a) is respectfully requested.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 9, 14, 15 and 22 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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